

切片检查报告

MICROSECTION INSPECTION

铜厚、焊锡厚阻焊油墨厚 Thickness Measurements of Copper, Solder, Solder Mask (Unit: um)

项目 Items		孔铜 Hole Wall Cu						焊锡厚 Solder Thickness		阻焊油墨 Solder Mask		
		A	B	C	D	E	F	Hole(avg.)	SMT	A	T	L
要求 Requirement		按资料要求 MI Requirement≥18						≥1-40um		≥10	≥10	≥10
结果 Result	#1								/			
	#2											
	#2											

阻焊 Solder Mask 样本位置 Specimen Locations 孔壁的镀铜、焊锡 Hole Wall Cu,Solder



孔粗，介质厚度 Measurements of Drilling Roughness and Dielectric Thickness (Unit: mm)

项目 Item		孔粗 Roughness	介质厚度 Dielectric Thickness					
要求 Requirement		≤25.4		/	/			
结果 Result	#1			/	/			
	#2							
	#3							

✓ 内在缺陷检查 Defects Inspection

项目 Item					Pass	Fail
钻污 Smear					ACC	
电镀空穴 Plating Void					ACC	
镀层破裂 Plating Crack					ACC	
披锋/瘤粒 Burrs and Nodules					ACC	
露纤维 Glass Fiber Protrusion					ACC	
焊盘浮离 Pad Lifted Land					ACC	
层间分离 Separation Between Layers					ACC	
孔铜剥离 Pull Away of Hole Copper					ACC	
内层连接断裂 Connection Separation Between internal Layer					ACC	
评论Remarks:						
Inspected By 检验员		Date 日期		Approved By 审核		Date 日期